

Packaging Strategy for High Voltage and High Shock Environments

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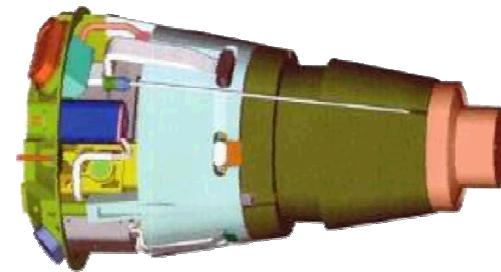


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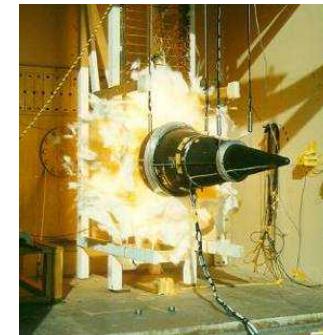
Outline

- Problem Statement
- Background
 - Current Packaging Strategy
 - High Voltage Breakdown
- Approach
 - New Packaging Strategy
- Testing and Validation
 - High Voltage Testing
 - Contact Angle Testing
 - Dielectric Strength Testing
 - Adhesion Characterization
- Conclusions
- Future work



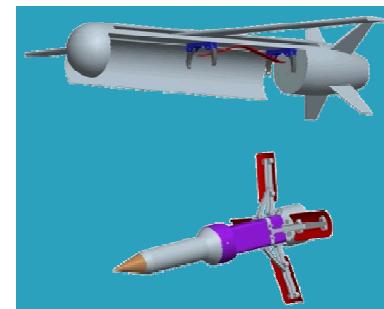
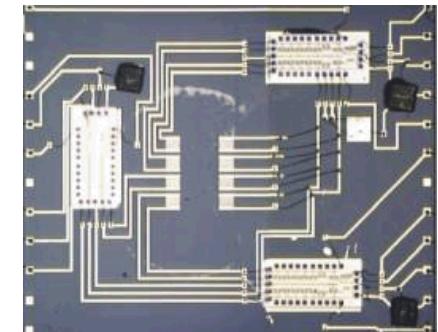
Problem Statement

It is the intent of this study to develop a new packaging strategy that will eliminate the cumbersome design issues associated with the legacy encapsulation packaging strategy currently used in high voltage, high impact applications.



Background

- What are we packaging?
 - Electronic components on Printed Circuit Boards (PCBs)
- Where are PCBs used?
 - Everywhere
 - Compact
 - Low and high voltage
 - Multi-layer traces and components
- Why do we package PCBs?
 - Operating environment
 - Coated
 - Fastened
 - Encapsulated



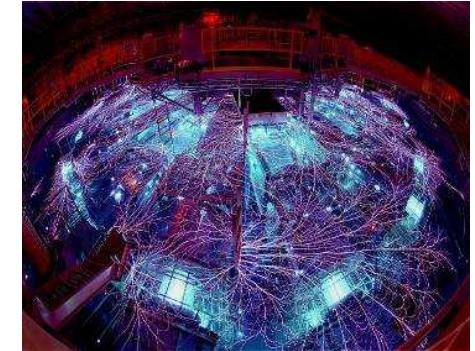
Background

- Sandia's Current Packaging Strategy for High Voltage High Impact Environments
 - Utilizes an epoxy encapsulant
 - Filled system - Glass Micro Balloons
- Pros
 - Prevents electrical breakdown
 - Provides impact protection
- Cons
 - Thermal stresses
 - Rework is difficult
 - Heavy



Background

- 3 types of high voltage breakdown
 - Internal discharge
 - Surface discharge
 - Corona discharge
- Goal is to improve packaging strategy while preventing breakdowns
 - Strong dielectric
 - Adheres well
 - Complete coverage
- Investigate conformal coatings



Approach

- **New Packaging Strategy**
 - Coat with a Conformal Coating
 - Package with a Foam
- **Pros Coating**
 - Prevents electrical breakdown
 - Provides component protection
 - Rework is feasible
- **Pros Foam**
 - Provides impact protection
 - Rework is still feasible
 - Light 4lbs instead of 65lbs
- **Pros Combination**
 - Can optimize coating and foam combinations for operating environment

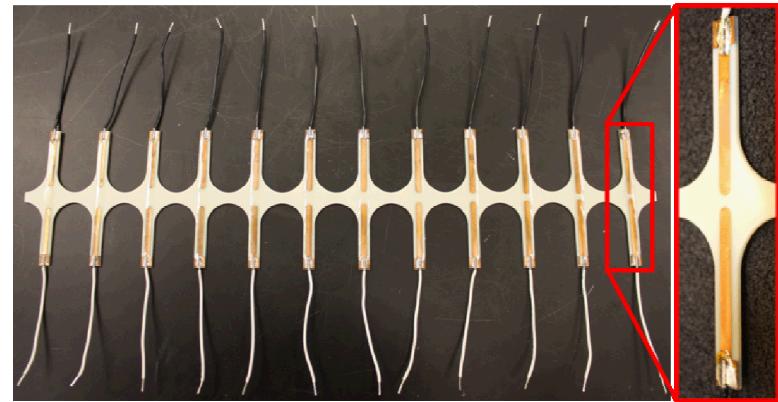
Developing New Strategy

- Coatings
 - Selected Coatings
 - Commercial
 - In House
 - Application Techniques
 - Brush
 - Syringe
 - Spray
 - Vapor Deposition

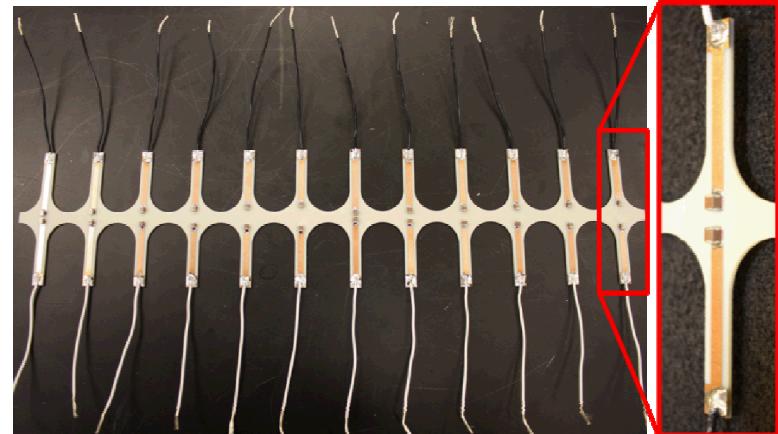
Material	Form	Cure	Intended Use	Tg (°C)
828/DEA	2 Part liquid	Thermal	Adhesive/Encapsulant	71
HA-84	1 Part liquid	UV and Thermal	Coating	85
Dymax X-617-11-1	1 Part liquid	UV	Coating	65
Humiseal UV40	1 Part liquid	UV and Thermal	Coating	45
Uralane 5750	2 Part liquid	Thermal	Adhesive	-60
Dymax 9481	1 Part liquid	UV and Thermal	Coating	65
Dymax 984	1 Part liquid	UV and Thermal	Coating	69
Dymax 920557	1 Part liquid	UV and Thermal	Coating	80
828/D230	2 Part liquid	Thermal	Adhesive	70
TurboCoat	1 Part Aerosol	RT	Coating	53
Fine-L-Kote	1 Part Aerosol	RT	Coating	45
Masterbond UV15	1 Part liquid	UV	Coating	125
Parylene C	1 Part solid	Vapor Deposition	Coating	90
Emcast 1902	1 Part liquid	UV	Coating	63
Emcast 1910	2 Part liquid	UV and Thermal	Coating	63
828/DEA w/ 4% Cabosil	2 Part liquid	Thermal	Adhesive/Encapsulant	71
Cytec EN4/EN11 w/ 4% Cabosil	2 Part liquid	Thermal	Adhesive	-60
828/GMB/DEA	2 Part liquid	Thermal	Adhesive/Encapsulant	71

Developing New Strategy

- Test Coatings Electrically
 - Test Geometry
 - Flat traces
 - 12 gaps
 - Ranging from .01 to .52 inches

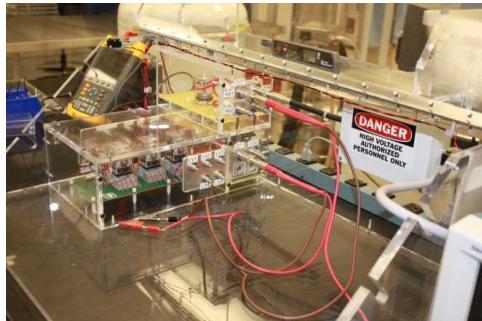


- Components
 - 6 gaps-repeated
 - Ranging from .05 to .425 inches



Developing New Strategy

- Apply load to test geometry
 - High Voltage Safety Box

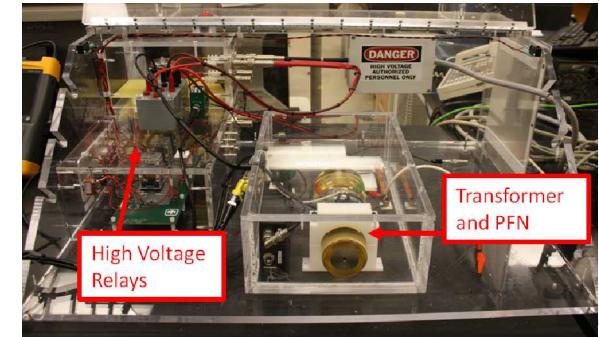


- DC Test System
 - 0 to 20 kV range
 - Test Procedure
 - Start at 1kV
 - Applied for 10 seconds
 - Stepped up in 1kV increments
 - Finish at max of 20 kV



- AC Test System

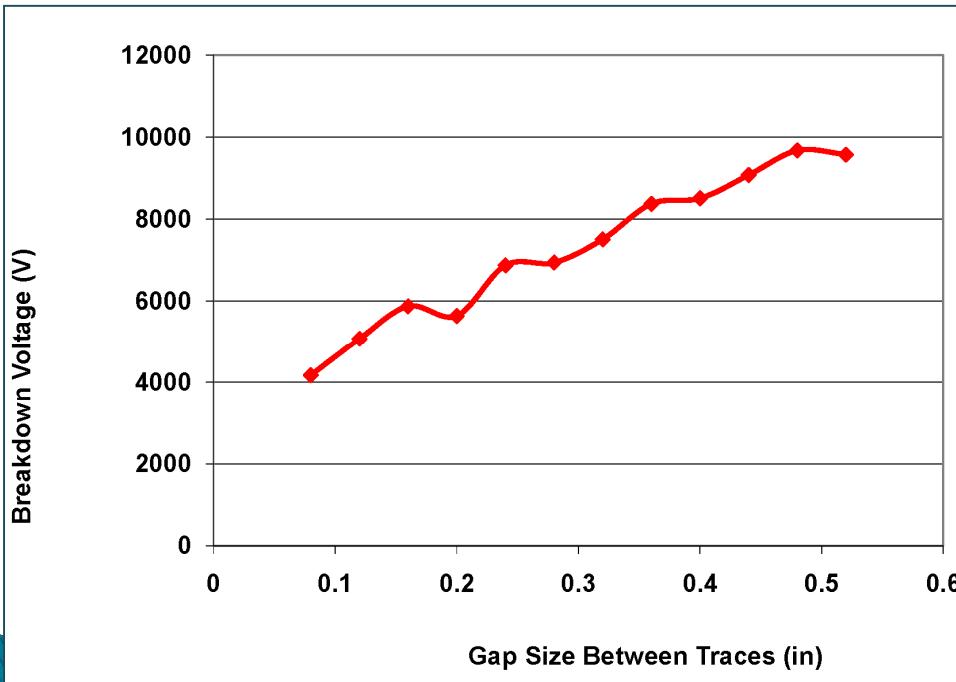
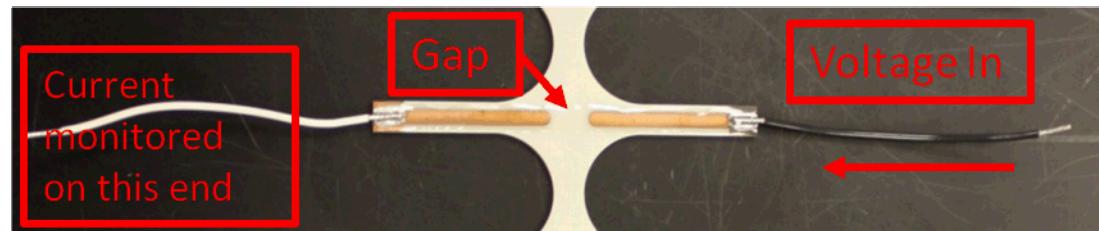
- 20 to 100 kV range
- Test Procedure
 - Start at 20kV
 - Applied a $13\mu\text{s}$ pulse
 - Stepped up in $\sim 10\text{kV}$ increments
 - Finish at max of 100 kV



- Labview Interface

Initial Electrical Testing

- Detecting breakdowns across a gap



- Flat trace geometry
- No coating
- Breakdown voltage vs. Gap in ambient air
- Baseline established

Initial Electrical Testing

- Coatings on flat trace geometry
 - .01 to .52 inch gaps

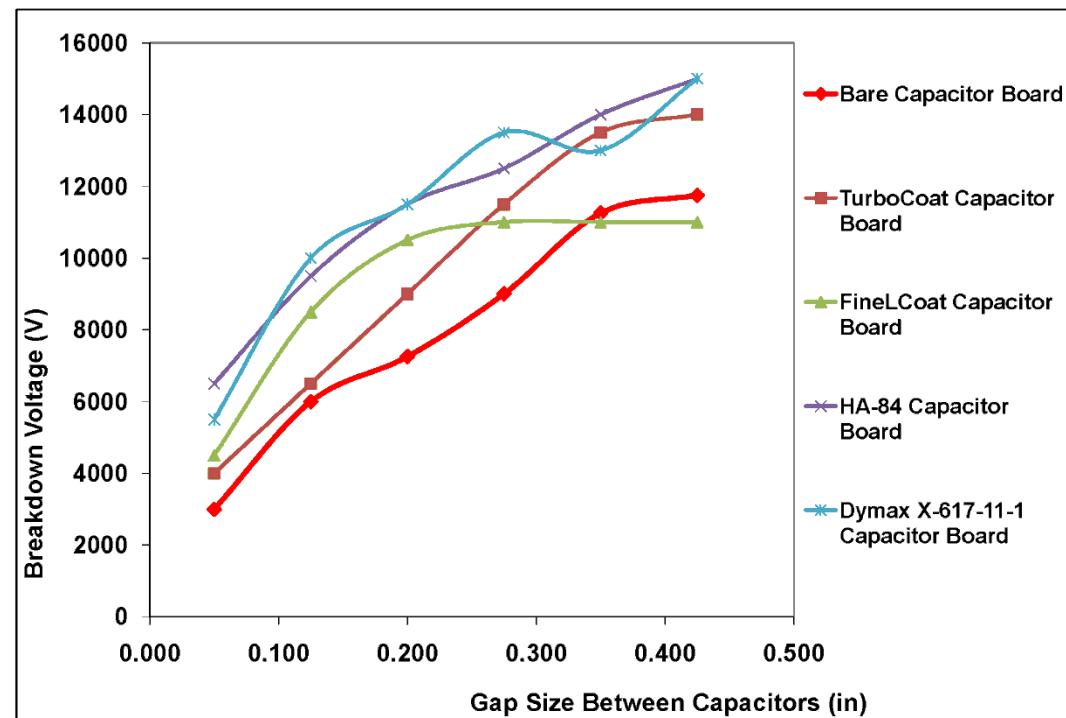
- Applied coatings
 - Brush
 - Syringe
 - Aerosol

- DC test
- Outperformed DC system
 - Except aerosol coatings
 - 1 coat, thin

Coating	Thickness (in)	Gap Size (in)	Breakdown Voltage (Volts)
None	N/A	0.010	900
Humiseal UV40	0.021	0.010	>20000
Uralane 5750 Hand applied	0.011	0.010	>20000
HA-84 Brushed on (2 coats)	0.042	0.010	>20000
Dymax X-617-11-1	0.017	0.010	>20000
Dymax 920557	0.030	0.010	>20000
Fine-L-Kote	0.007	0.010	9000
Turbo-Coat	0.006	0.010	18000

Initial Component Electrical Testing

- Component Geometry
- Uncoated Board
- Select Coatings Applied
 - HA-84 and Dymax >20kv on flat trace
 - Aerosol- 3 coats
- DC System Testing
- Protruding Geometries with sharp edges present issues



Coating Sharp Edges

- Address corner coverage
 - Aerosol coatings in 3 coats
 - Fluoresce under UV light



- Components are a challenge
 - Sharp Corners
 - Thin coverage
 - High electrical field concentration

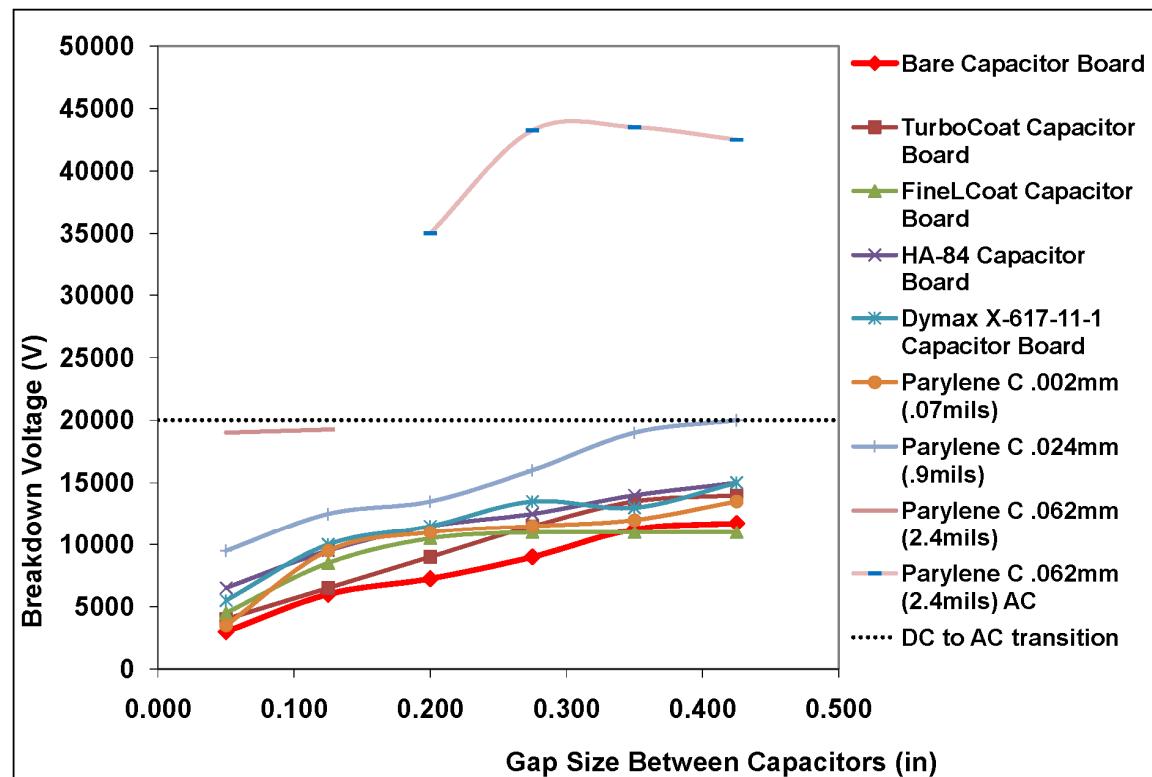
Uniform Coating on Protruding Geometries

- Prove corners can be protected

- Parylene C

- Vapor deposition applies uniformly to all surfaces

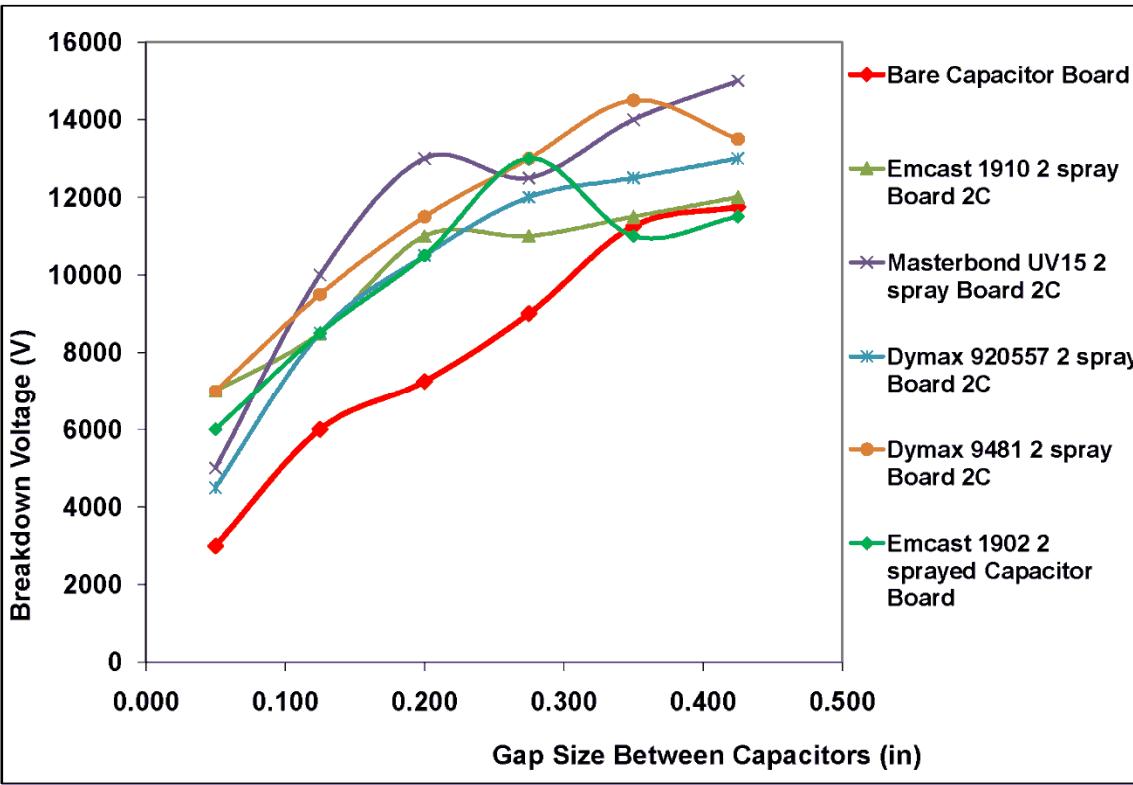
- Applied in 3 coating thicknesses



Spray Coating Development

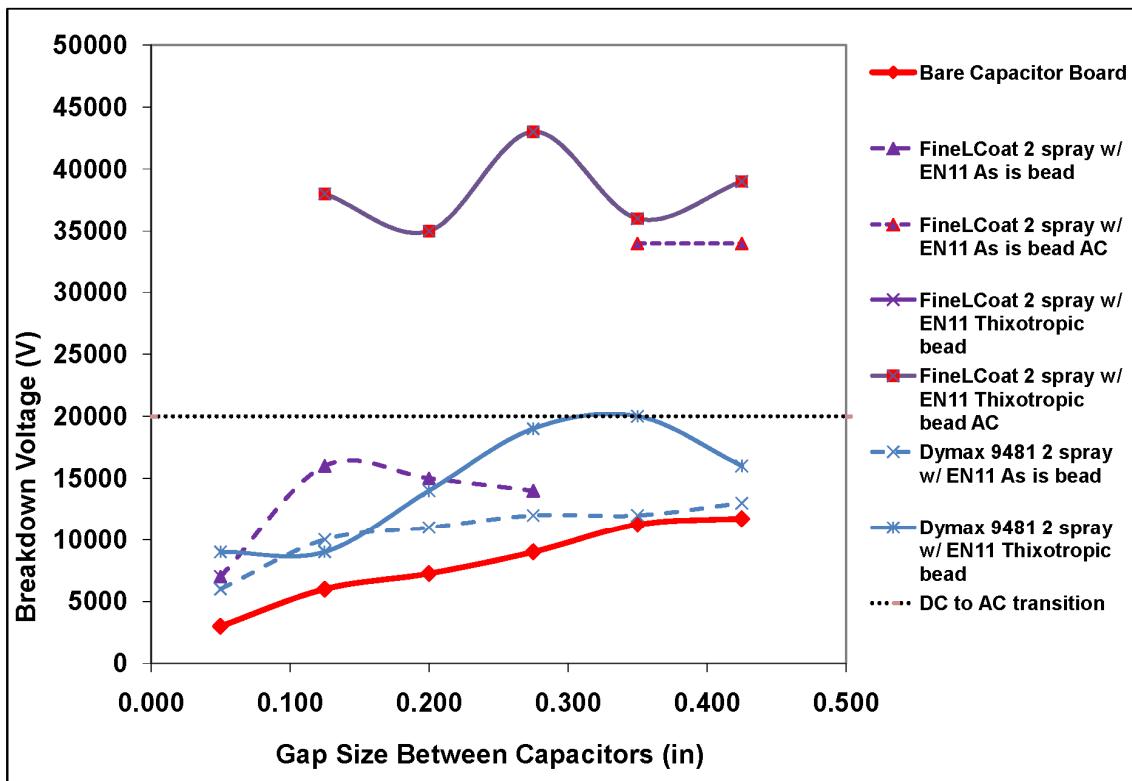
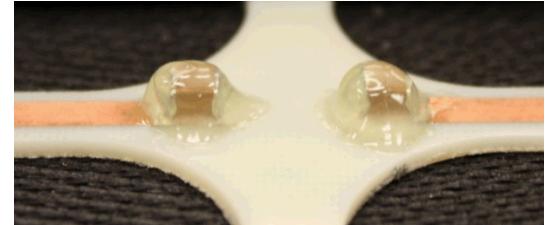
- Corners can be protected
 - Uniform coverage

- Spray coating technique developed
- Coatings down selected to spray capable materials
- Sprayed component test boards
- DC tests– still breaking down



Bead Coating Development

- Apply bead coat to high voltage components
 - EN11 in two versions
 - As is – dashed line
 - Thixotropic – solid line



- Thixotropic outperforms As is
- Uniform coverage critical

Bead Coating Strategy

- Bead Coat High Voltage Components

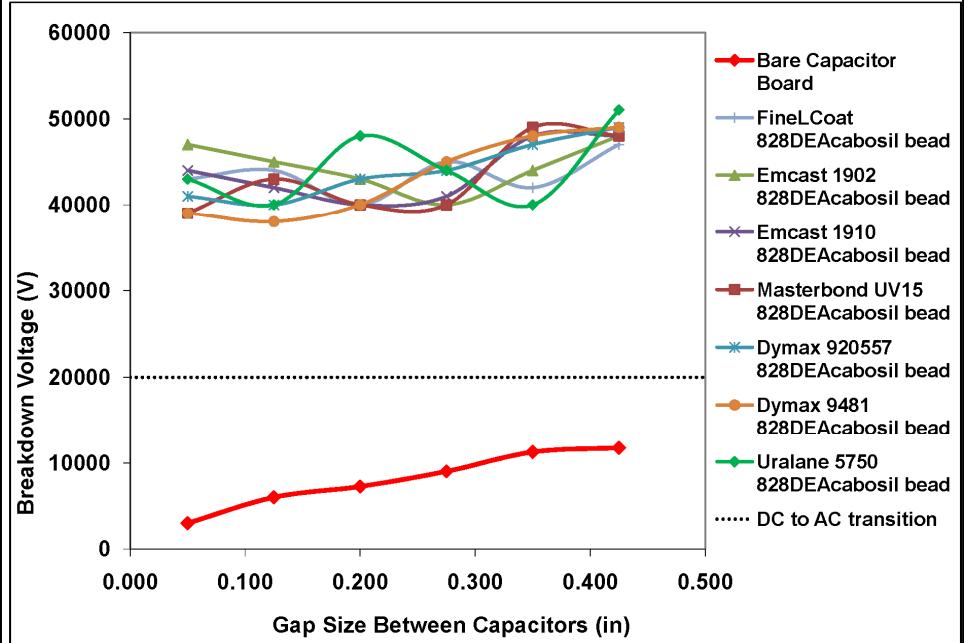
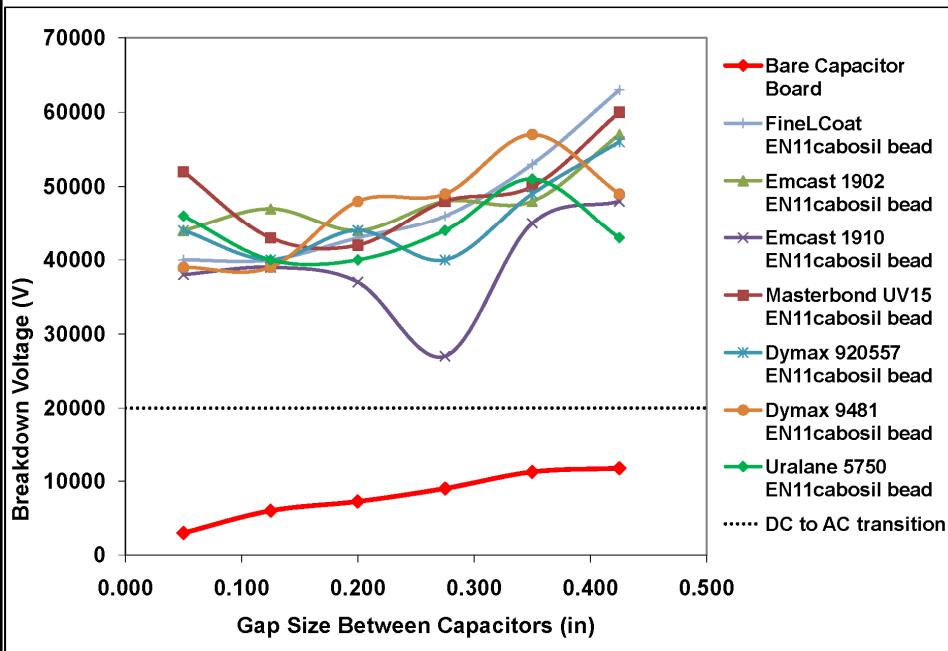
- Two types of bead material

- EN11 thixotropic

- Low Tg

- 828/DEA thixotropic

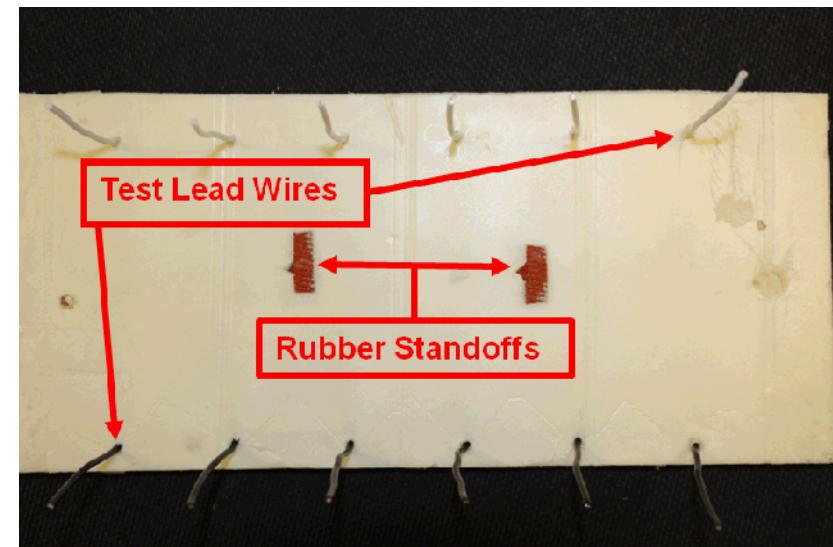
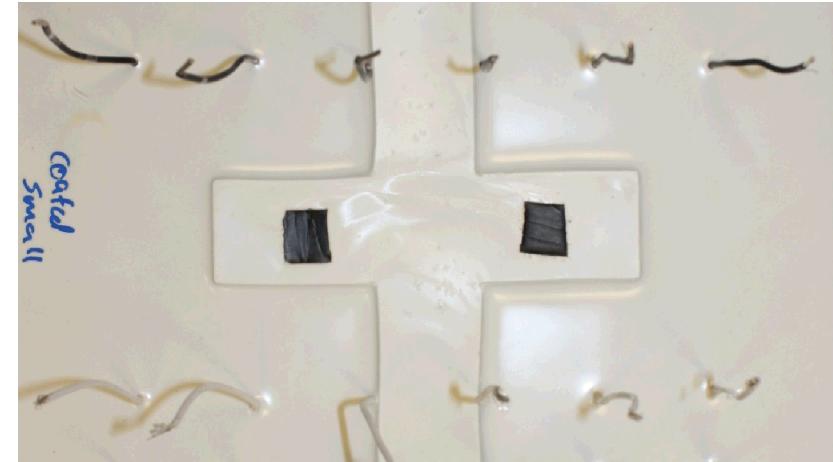
- High Tg



- Breakdown protection 40 to 65kV

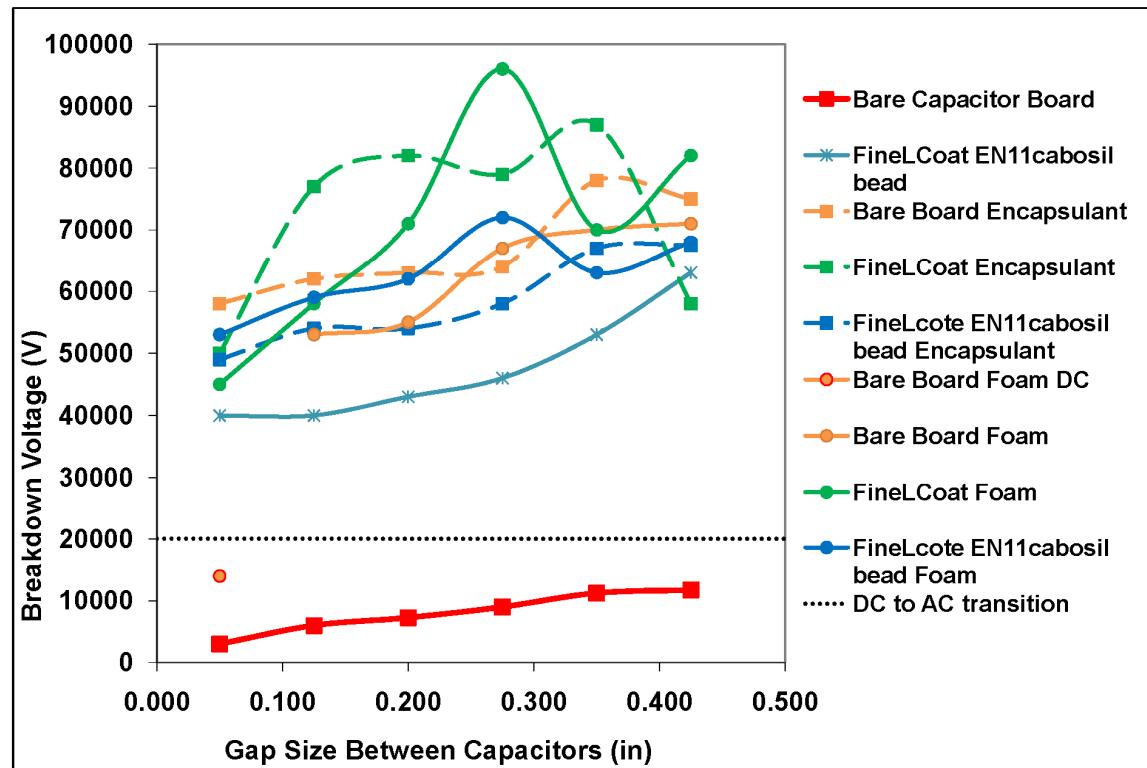
New vs. Legacy Packaging Strategy

- Compare
- Epoxy encapsulant
 - 828/GMB/DEA
 - vs.
- Foam encapsulant
 - PMDI foam
- Three board configurations for each packaging strategy
 - Uncoated capacitor board
 - Coated capacitor board
 - Coated and bead capacitor board



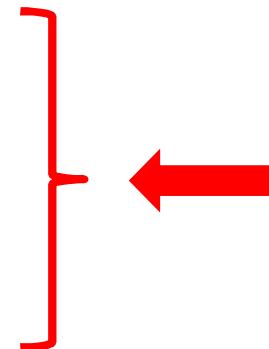
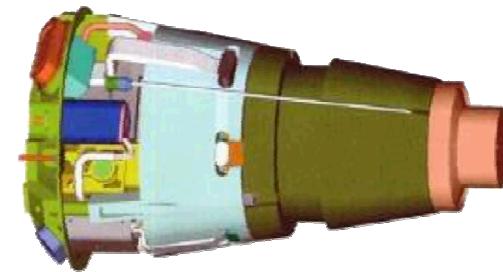
New vs. Legacy Electrical Testing Results

- Epoxy Encapsulant vs.
- Foam Encapsulant
- Comparable Breakdown Voltages
- Foam alone
 - Provide mechanical rigidity
 - Skin acts as a dielectric
- New strategy is electrically capable and equivalent



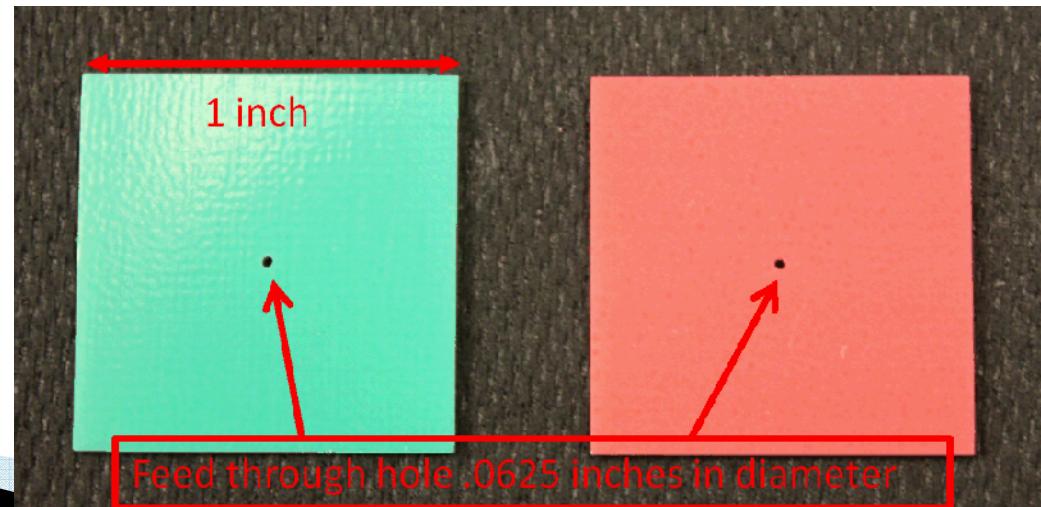
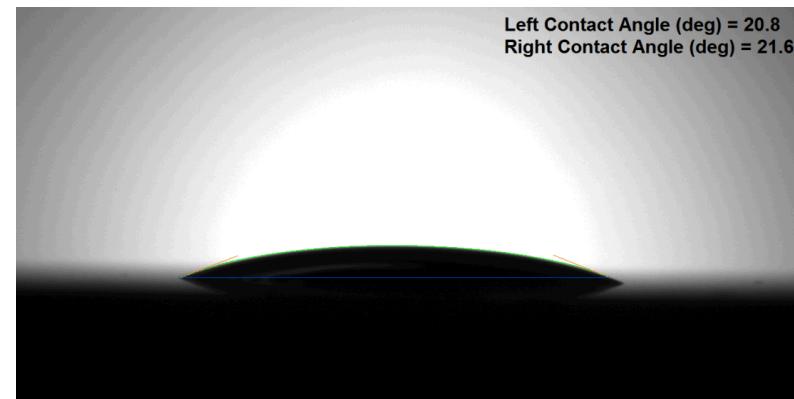
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Contact Angle Testing

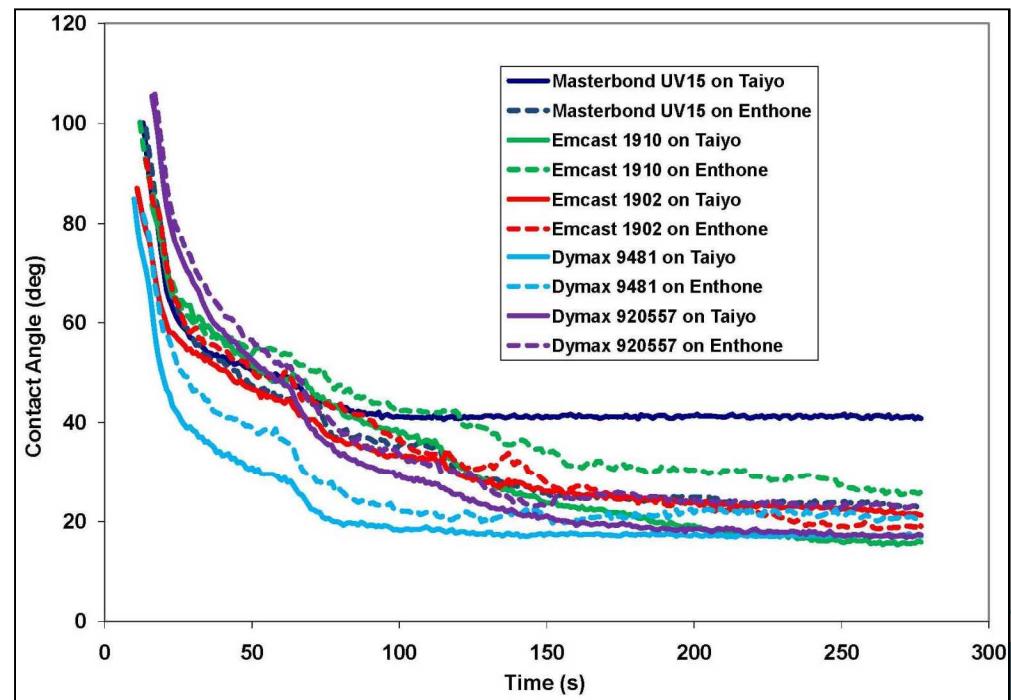
- Two types of solder mask
 - Screen Printed Red Enthone
 - Spray Applied Green Taiyo
- Feed-Through-Goniometer
- Contact angle vs. time



Contact Angle Results

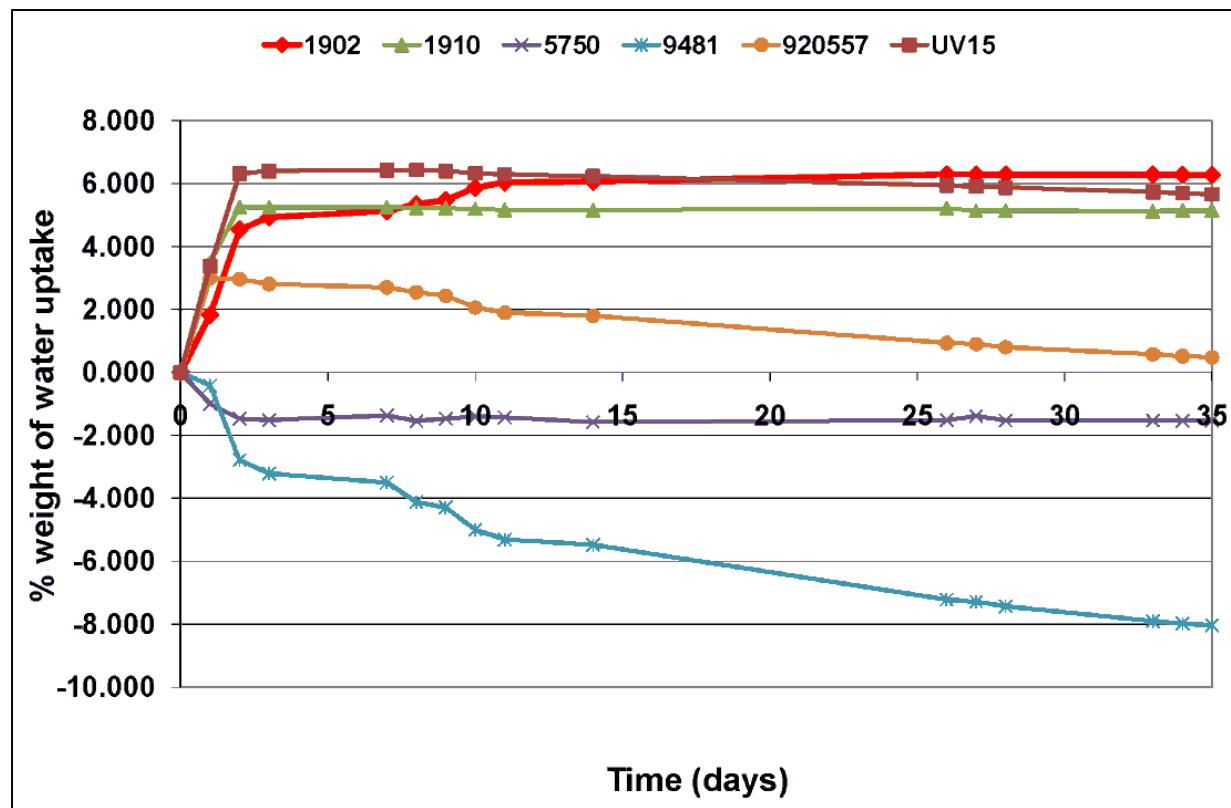
- Contact angle vs. time
- Red solder mask results are dashed lines
- Green solder mask results are solid lines
- Equilibrium is reached in 3 minutes

- All coatings capable of wetting solder mask surfaces
- Green Taiyo solder mask preferred class



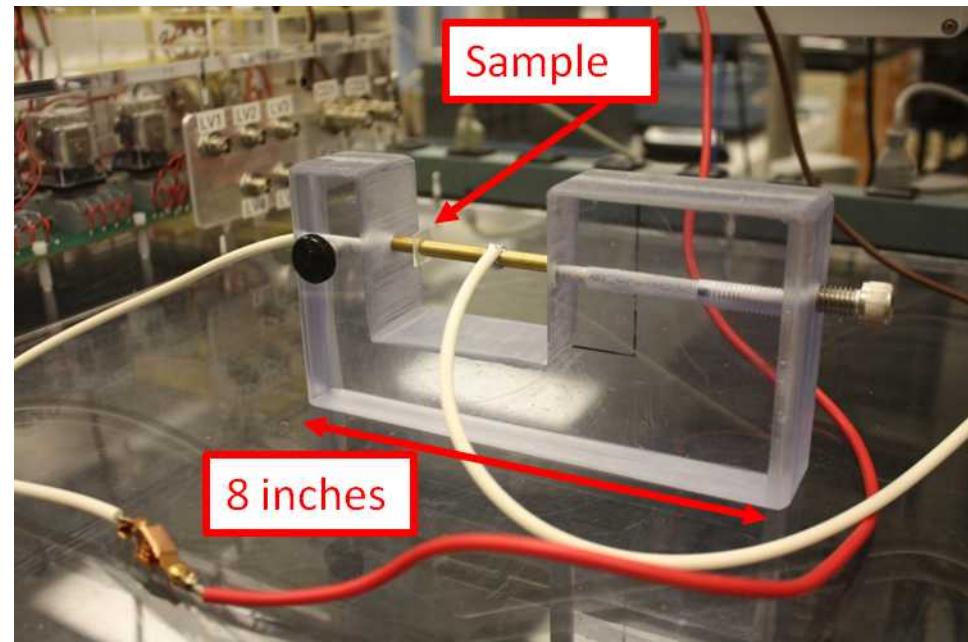
Water Uptake Study

- Package for operating environment – Humid
- Square plaques of bulk material
- Submersed in 70°C DI water
- Monitored weight for 35 days
- Strong activity in 5 days
- Either absorb or resist water
- Saturated in about 10 days
- Continued weight loss



Dielectric Strength Testing

- Bulk dielectric strength of coatings
- Square plaques of bulk material
- Submersed in 70°C DI water
- Monitored weight gain for two weeks
- Tested electrically



Dielectric Strength Results

- Unaged vs. 2 week aged dielectric strength
- Water does impact dielectric strength
- Coatings resistance to water maintain dielectric strength
- Customize coating selections based on operating environment

ASTM D149	Dielectric Strength unaged (V/mil)	Dielectric Strength 2wk 100%RH at 70C aged (V/mil)	% reduction in Dielectric Strength from 2wk 100%RH at 70C aged (V/mil)	% weight gain of water (g)
HA-84	2056	1250	39	2
Dymax X-617-11-1	1045	432	59	3
Humiseal UV40	1070	1100	approx 0	-1
Uralane 5750	1186	1214	approx 0	0
Dymax 9481	2167	1477	32	-3
Dymax 920557	1300	1379	approx 0	1
828/D230	1727	1577	9	2
Emcast 1902	2769	1200	57	1
Emcast 1910	1364	895	34	5

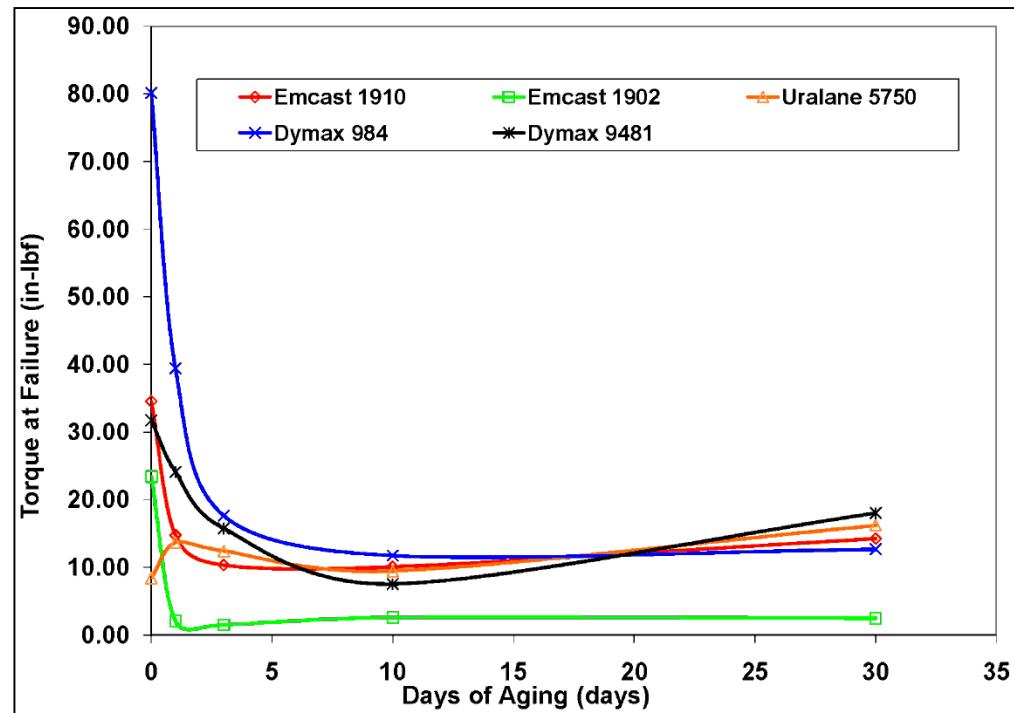
Napkin Ring Adhesion Testing

- Napkin Ring Geometry
 - Two substrates- S.S. and composite
 - Bonded together with an annulus of coating
 - Targeting PCB to coating interface
- Torsion tested
- Torque load at failure



Napkin Ring Adhesion Results

- Aging Study
 - 70°C at ~100% RH
 - 0, 1, 3, 10, 30 day aging times
 - Two samples per configuration

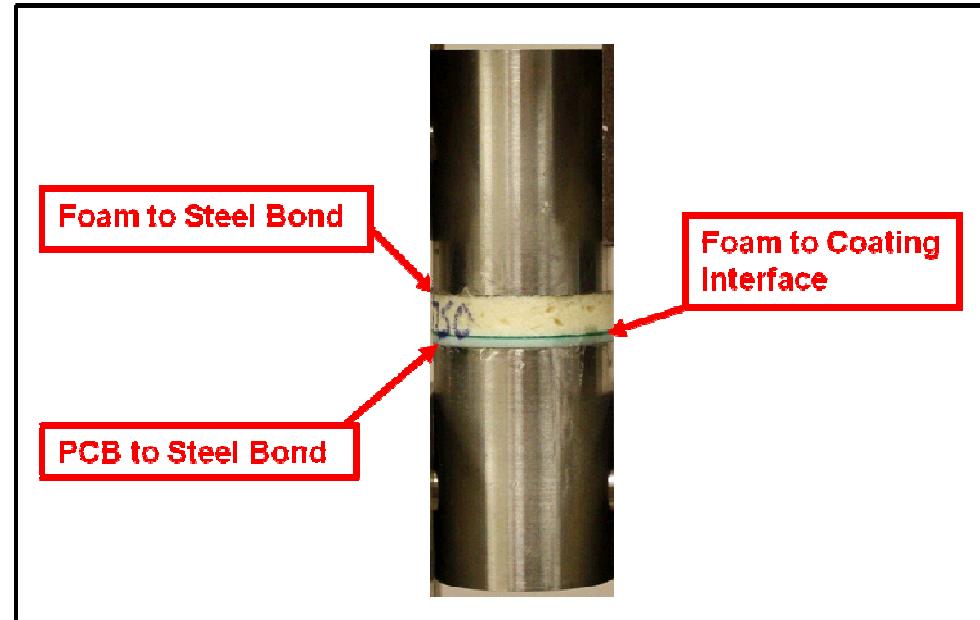


- All but 5750 experiences some loss in adhesion strength

- Compare to a 0 day 828/GMB/DEA napkin ring strength of 235 in-lb

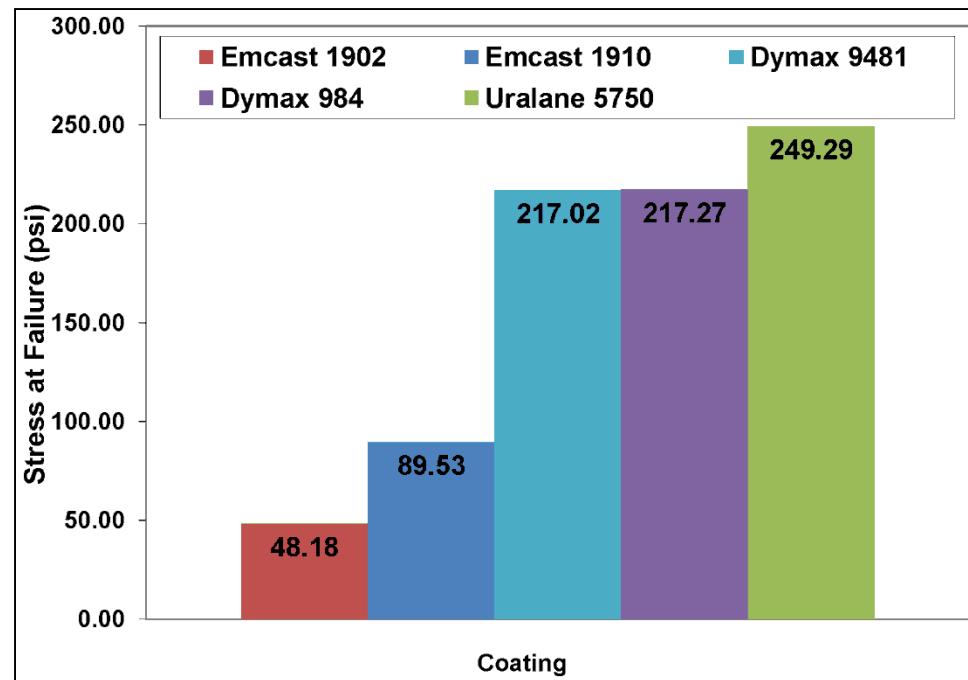
Butt Tensile Adhesion Testing

- Butt tensile geometry
 - Two substrates and test interface
 - Foam adhesion cured directly on coating
 - Targeting PCB with coating to foam interface
- Tested in axial tension
- Stress at failure



Butt Tensile Adhesion Results

- Two samples per configuration
- All failed at coating to foam interface



- Compare to 828/GMB/DEA strength of 5200 psi

Conclusions

- Coating for flat traces and bead coating for protruding geometries can provide breakdown protection in the 40–65kV range depending on gap size
- The addition of foam can increase the electrical breakdown protection to 50–80kV range
- New packaging strategy vs. legacy packaging strategy
 - Equivalent from an electrical performance stand point
- Contact angle of coatings not impacted by type of solder mask
- Napkin ring and butt tensile adhesion strengths of coatings not as strong as legacy encapsulant, but adhesion is present
- Dielectric strength and adhesion can vary in a humid environment depending on the coating choice

Conclusions

- Approach was on target for the new packaging strategy
 - Coat with a conformal coating and bead coating
 - Package with a foam
- Coating
 - **Proven**
 - Prevents electrical breakdown
 - Provides component protection
 - **Still applicable**
 - Rework is feasible
- Foam
 - **Proven**
 - Prevents electrical breakdown
 - **Still applicable**
 - Can provide impact protection
 - Rework is still feasible
 - Light 4lbs instead of 65lbs
- When Combined
 - Option of optimizing coating and foam combinations for operating environment

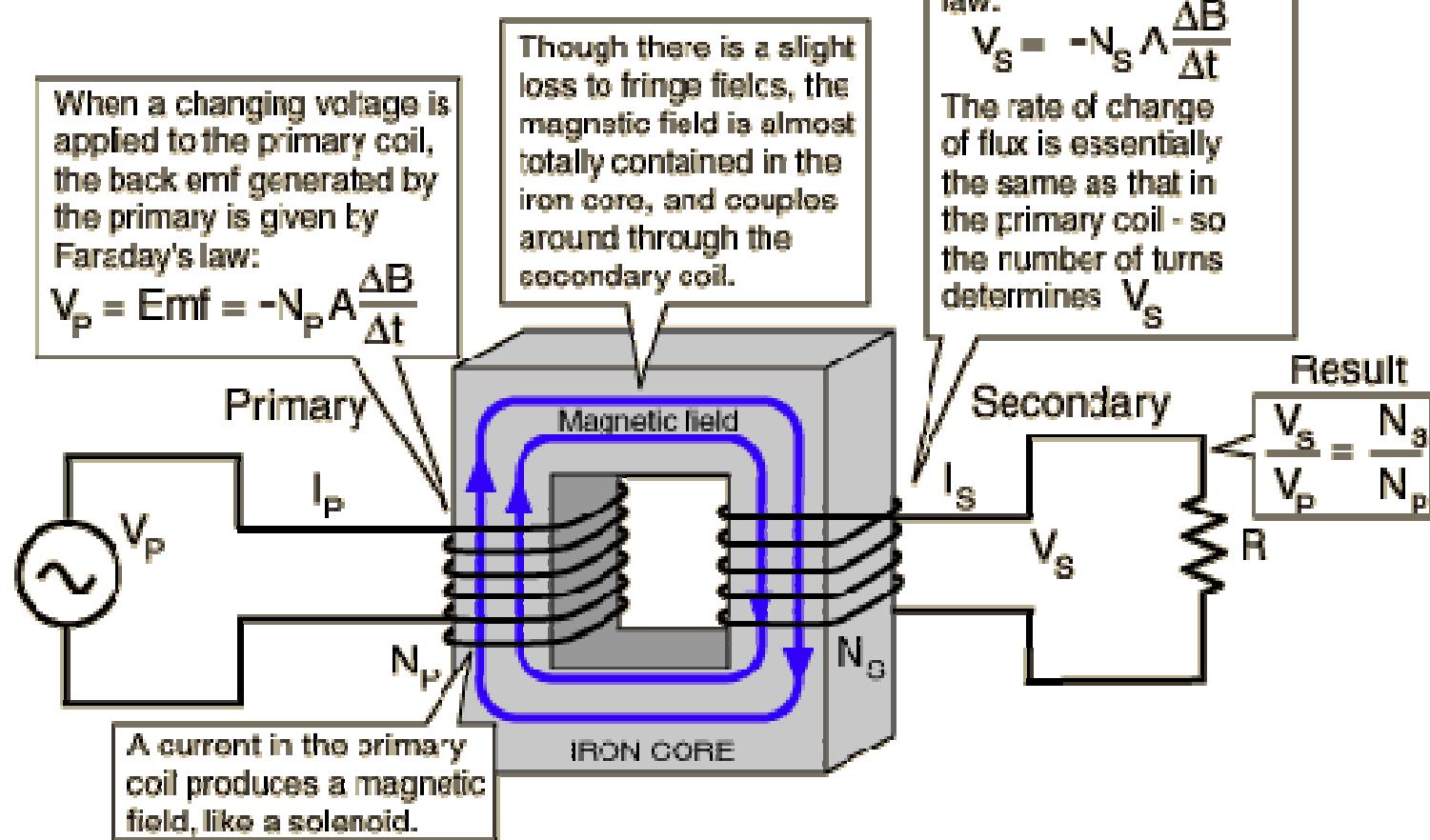
Future Work

- Larger test matrix to develop statistics
 - Would answer the question if polymers can be generalized in voltage breakdown strength
 - Age foam to asses its performance in a humid environment
- Develop a greater understanding for the behavior of the UV systems
 - adhesion differences between typical epoxy systems and the UV systems
 - Tg was measured on DSC, compare to TMA or DMA
 - Cohesive failure
- Test/Model packaging strategies in real applications for high voltage and high impact performance using combinations of coatings types and foam densities

Questions or Comments

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AC Test System -Transformer



TBJ Test Coupon

